MA21D38

Silicon epitaxial planar type

For high frequency rectification

■ Features

- $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltag V_F
- High non-repetitive peak forward surge voltage

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	30	V	
Maximum peak reverse voltage	V_{RM}	30	V	
Forward current (Average)	I _{F(AV)}	1.0	A	
Non-repetitive peak forward surge current *	I _{FSM}	20	A	
Junction temperature	T_j	125	°C	
Storage time	T _{stg}	-55 to +125	°C	

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

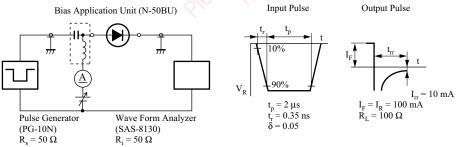
Unit: mm 0.60±0.10 0.80±0.10 0.80±0.10 0.16±0.10 0

Marking Symbol: 3U

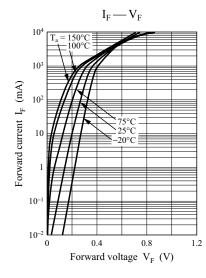
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

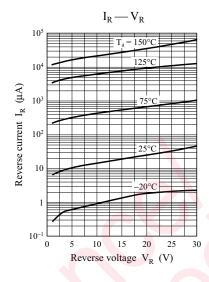
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_{\rm F} = 0.5 {\rm A}$	S 76	0.34	0.38	V
	V_{F2}	$I_F = 0.7 A$	11/0	0.36	0.40	
	V_{F3}	$I_{\rm F} = 1.0 \; {\rm A}$	300 25	0.38	0.42	
Reverse current	I_R	$V_R = 30 \text{ V}$	2/10		100	μΑ
Terminal capacitance	Ct	$V_R = 10 \text{ V, } f = 1 \text{ MHz}$	19	40		pF
Reverse recovery time *	t _{rr}	$egin{aligned} I_F = I_R = 100 \text{ mA}, & I_{rr} = 10 \text{ mA}, \\ R_L = 100 \Omega & \end{aligned}$		13		ns

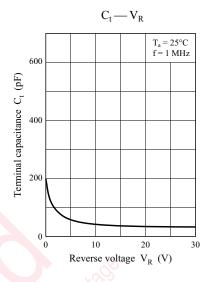
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. *: t_{rr} measurement circuit

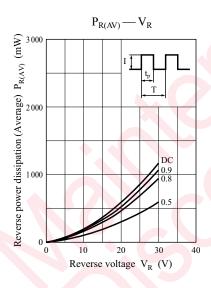


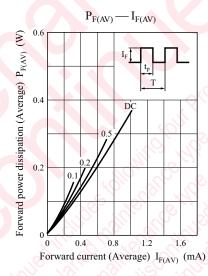
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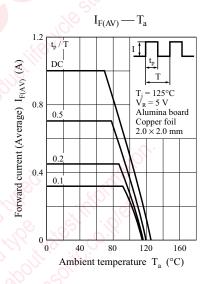


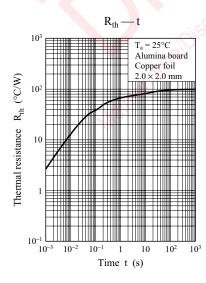












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